



Description

JMT P-channel Enhancement Mode Power MOSFET

Features

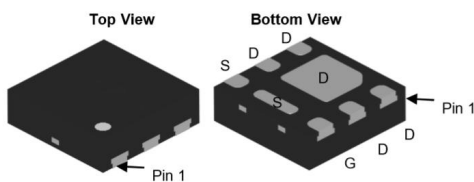
- $V_{DS} = -30V$, $I_D = -11A$
 $R_{DS(ON)} < 20m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)} < 31m\Omega$ @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Application

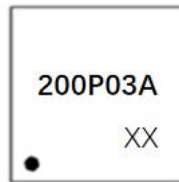
- PWM Applications
- Load Switch
- Power Management



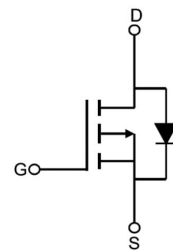
100% UIS TESTED!



DFN2020-6L



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel (pcs)	Per Carton (pcs)
200P03A	JMTV200P03A	TAPING	DFN2020-6L	7"	3000	120000

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-11
		$T_C = 100^\circ C$	-7.2
I_{DM}	Pulsed Drain Current ^{note1}	-44	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}	49	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	9.6
$R_{\theta JC}$	Thermal Resistance, Junction to Case	13	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$



Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} =0V,	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = -250μA	-1.0	-1.5	-2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance <small>note3</small>	V _{GS} = -10V, I _D = -10A	-	16	20	mΩ
		V _{GS} = -4.5V, I _D = -5A	-	24	31	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -15V, V _{GS} =0V, f=1.0MHz	-	1432	-	pF
C _{oss}	Output Capacitance		-	186	-	pF
C _{rss}	Reverse Transfer Capacitance		-	147	-	pF
Q _g	Total Gate Charge	V _{DD} = -15V, I _D = -9.1A, V _{GS} = -10V	-	28	-	nC
Q _{gs}	Gate-Source Charge		-	5	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	6	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -15V, I _D = -6A, V _{GS} = -10V, R _{GEN} =2.5Ω	-	9	-	ns
t _r	Turn-on Rise Time		-	36	-	ns
t _{d(off)}	Turn-off Delay Time		-	34	-	ns
t _f	Turn-off Fall Time		-	43	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-11	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-44	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -11A	-	-	-1.2	V
t _{rr}	Reverse Recovery Time	I _F = -11A,	-	16	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	-	9	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. E_{AS} condition: Starting T_J=25°C, V_{DD}= -15V, V_{GS}= -10V, R_G=25Ω, L=0.5mH, I_{AS}= -14A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%



Typical Performance Characteristics

Figure 1: Output Characteristics

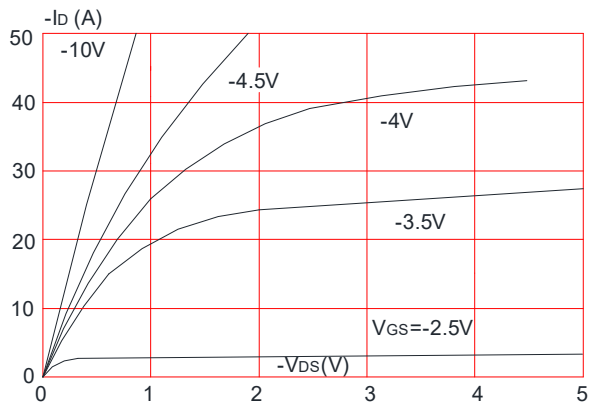


Figure 2: Typical Transfer Characteristics

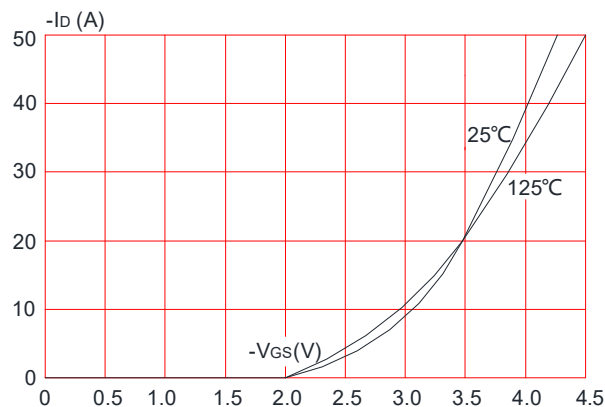


Figure 3: On-resistance vs. Drain Current

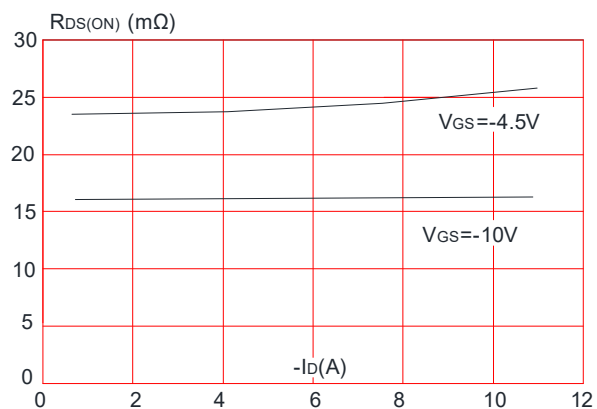


Figure 4: Body Diode Characteristics

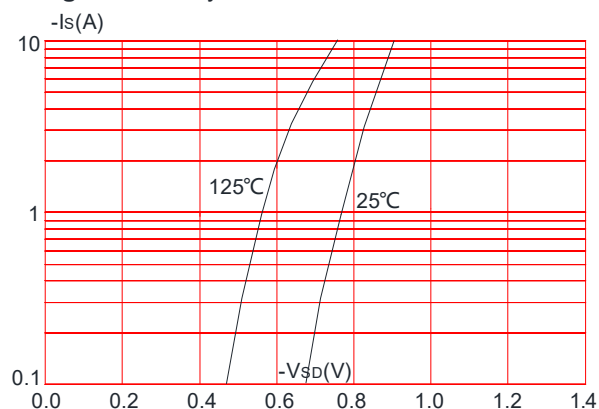


Figure 5: Gate Charge Characteristics

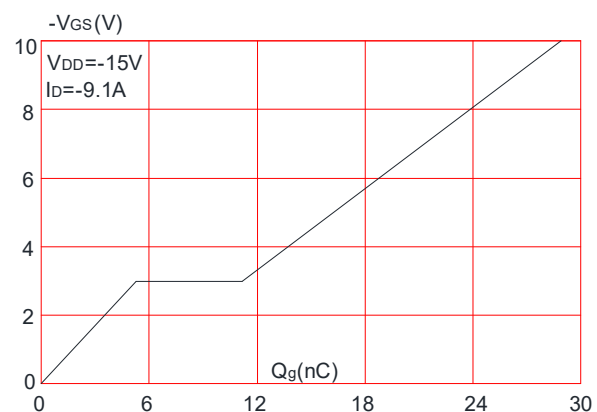


Figure 6: Capacitance Characteristics

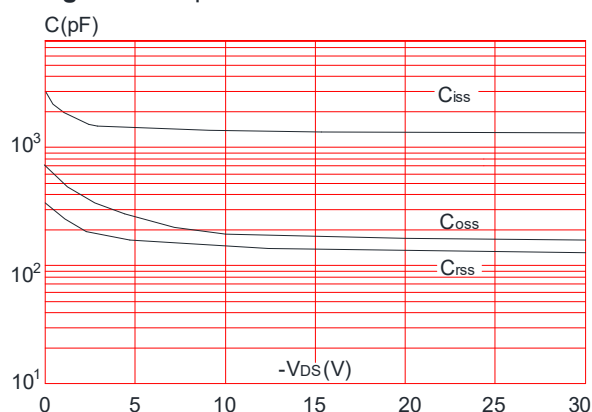




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

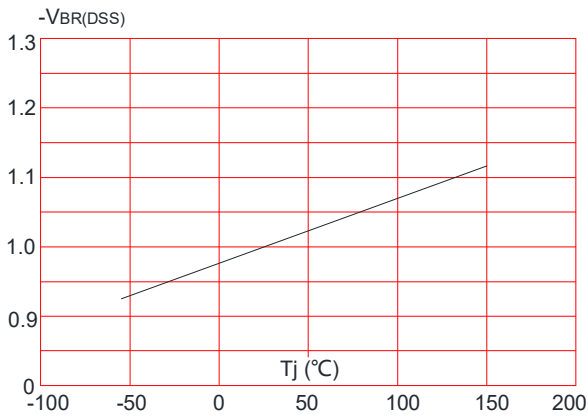


Figure 8: Normalized on Resistance vs. Junction Temperature

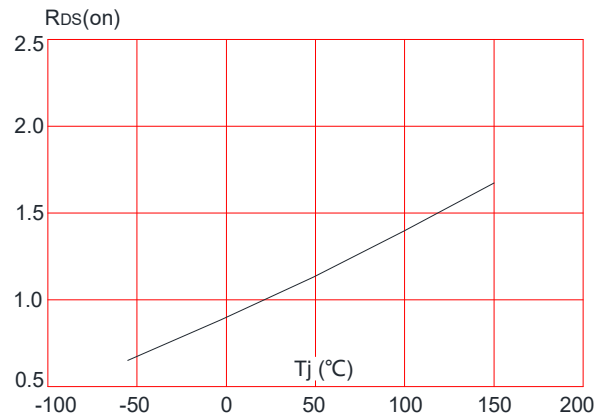


Figure 9: Maximum Safe Operating Area

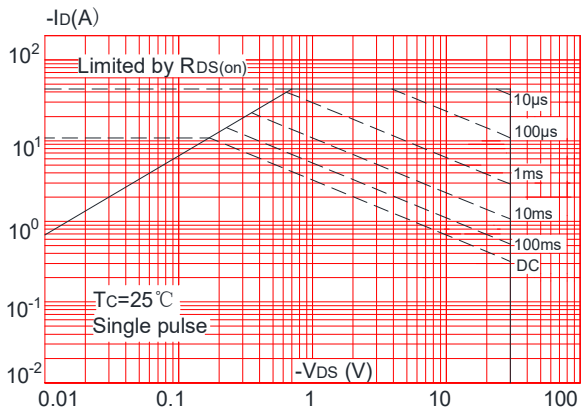


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

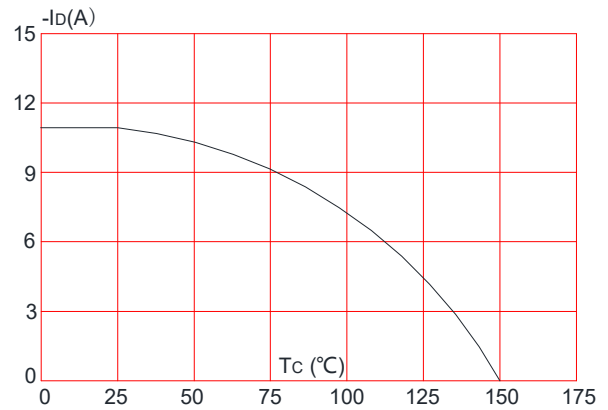
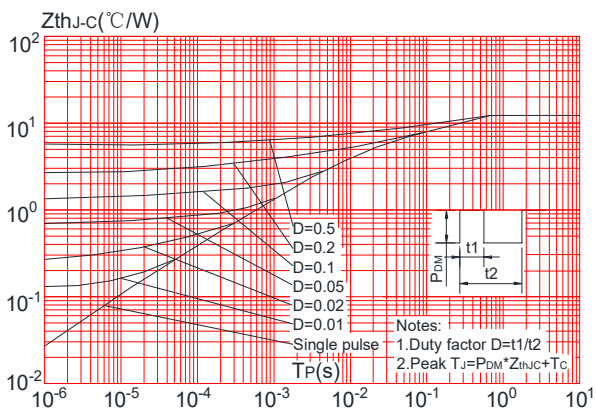
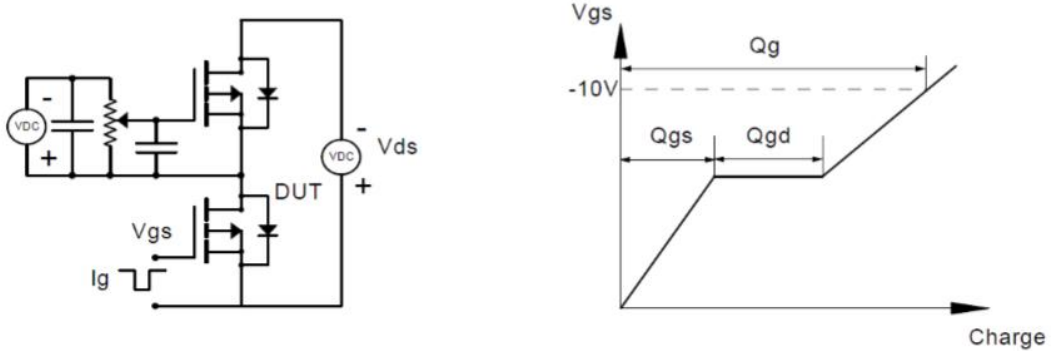


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

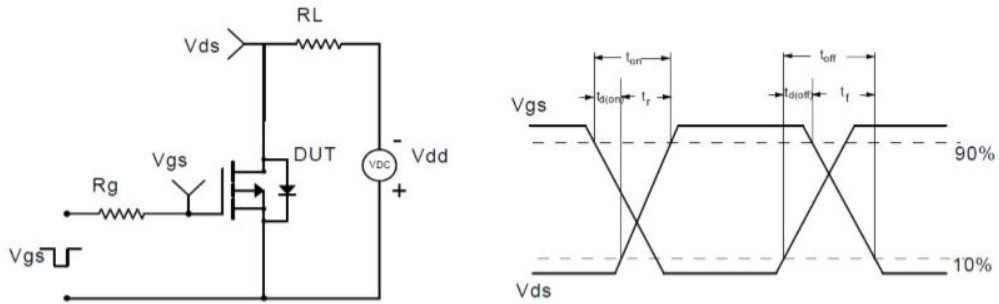


Test Circuit

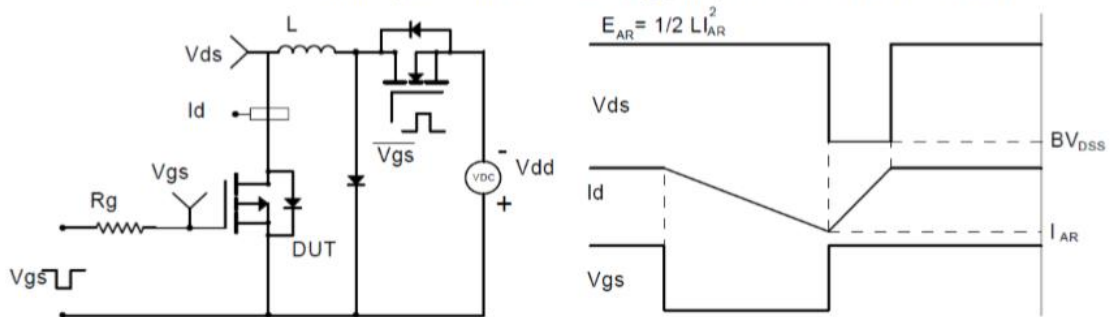
Gate Charge Test Circuit & Waveform



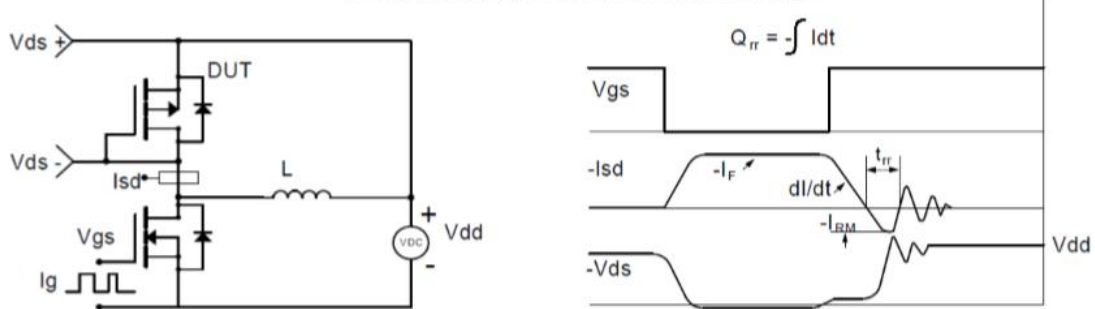
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

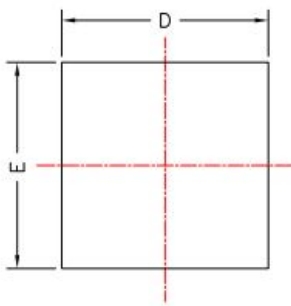


Diode Recovery Test Circuit & Waveforms

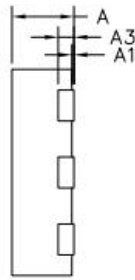




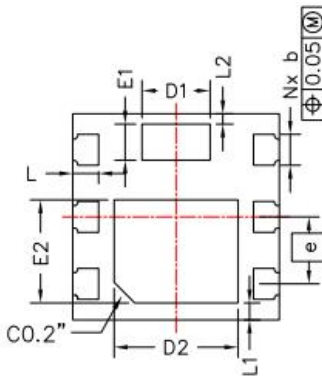
Package Mechanical Data-DFN2020-6L



Top View



Side View



Bottom View

SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.700	0.750	0.800	0.028	0.030	0.031
A1	---	---	0.050	----	----	0.002
A3	0.195	0.203	0.211	0.008	0.008	0.008
b	0.250	0.300	0.350	0.010	0.012	0.014
e	0.65BSC			0.026 BSC		
D	1.900	2.000	2.100	0.075	0.079	0.083
E	1.900	2.000	2.100	0.075	0.079	0.083
D1	0.560	0.660	0.760	0.022	0.026	0.030
E1	0.250	0.350	0.450	0.010	0.014	0.018
D2	1.100	1.200	1.300	0.043	0.047	0.051
E2	0.900	1.000	1.100	0.035	0.039	0.043
L	0.150	0.250	0.350	0.006	0.010	0.014
L1	0.065	0.165	0.265	0.003	0.006	0.010
L2	0.000	0.100	0.200	0.000	0.004	0.008

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